



Features

Configuation

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**DGD2190** 

#### **HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8**

Floating High-Side Driver in Bootstrap Operation to 600V

Output Drivers Capable of 4.5A/4.5A Typ Sink/Source

Schmitt Triggered Logic Inputs with Internal Pull-Down

Undervoltage Lockout for High and Low-Side Drivers

Extended Temperature Range: -40°C to +125°C

Logic Input (HIN and LIN) 3.3V Capability

Drives Two N-Channel MOSFETs or IGBTs in a Half-Bridge

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

Halogen and Antimony Free. "Green" Device (Note 3)

### Description

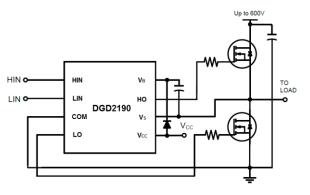
The DGD2190 is a high voltage/high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2190's high-side to switch to 600V in a bootstrap operation under high dV/dt conditions.

The DGD2190 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD2190 is offered in the SO-8 (Type TH) package and operates

### Applications

- **DC-DC Converters**
- **DC-AC Inverters**
- **AC-DC Power Supplies**
- Motor Controls
- **Class D Power Amplifiers**



**Typical Configuration** 

### Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD2190S8-13	DGD2190	13	12	2,500

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

#### and Lead-free

- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

Notes:



Characteria Control Contro DGD2190 = Product Type Marking Code YY = Year (ex: 16 = 2016)WW = Week (01 to 53)

over an extended -40°C to +125°C temperature range.

### **Mechanical Data**

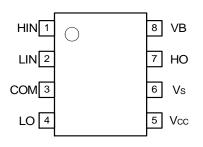
- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (B)
- Weight: 0.075 grams (Approximate)



SO-8 (Type TH) Top View



### **Pin Diagrams**

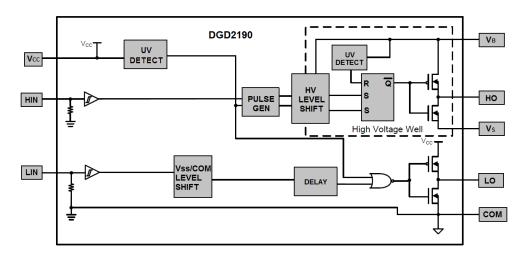


Top View: SO-8 (Type TH)

### **Pin Descriptions**

Pin Number	Pin Name	Function
1	HIN	Logic Input for High-side Gate Driver Output, in Phase with HO
2	LIN	Logic Input for Low-side Gate Driver Output, in Phase with LO
3	COM	Low-Side and Logic Return
4	LO	Low-Side Gate Drive Output
5	Vcc	Low-Side and Logic Fixed Supply
6	Vs	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	VB	High-Side Floating Supply

### **Functional Block Diagram**





### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	VB	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V
High-side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub> -0.3 to V <sub>B</sub> +0.3	V
Offset Supply Voltage Transient	dV <sub>S</sub> / dt	50	V/ns
Low-side and Logic Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V
Low-side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	Rejc	45	°C/W
Operating Temperature	TJ	+150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

# **Recommended Operating Conditions**

Parameter	Symbol	Min	Мах	Unit
High-side Floating Supply Absolute Voltage	VB	V <sub>S</sub> +10	V <sub>S</sub> +20	V
High-side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-side Floating Output Voltage	V <sub>HO</sub>	Vs	VB	V
Low-side Fixed Supply Voltage	Vcc	10	20	V
Low-side Output Voltage	V <sub>LO</sub>	0	V <sub>CC</sub>	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Notes: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

6. Logic operation for Vs of -5V to +600V. Logic state held for Vs of -5V to -VBs.



# **DC Electrical Characteristics** ( $V_{BIAS}$ ( $V_{CC}$ , $V_{BS}$ ) = 15V, $@T_A = +25^{\circ}C$ , unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	VIH	2.5	—	_	V	V <sub>CC</sub> = 10V to 20V
Logic "0" Input Voltage	VIL	—		0.8	V	$V_{CC}$ = 10V to 20V
High Level Output Voltage, V <sub>BIAS</sub> - V <sub>O</sub>	Vон	—	_	0.1	V	$I_0 = 0 m A$
Low Level Output Voltage, V <sub>O</sub>	V <sub>OL</sub>	—		0.035	V	$I_0 = 0 m A$
Offset Supply Leakage Current	I <sub>LK</sub>	—		50	μA	$V_{B} = V_{S} = 600V$
Quiescent V <sub>BS</sub> Supply Current	I <sub>BSQ</sub>	—	45	80	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V <sub>CC</sub> Supply Current	ICCQ	—	75	200	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I <sub>IN+</sub>	—	25	50	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	I <sub>IN-</sub>	—	1.0	2.0	μA	$V_{IN} = 0V$
V <sub>BS</sub> Supply Undervoltage Positive Going Threshold	V <sub>BSUV+</sub>	7.6	8.4	9.8	V	—
V <sub>BS</sub> Supply Undervoltage Negative Going Threshold	V <sub>BSUV-</sub>	6.9	7.8	9.0	V	_
V <sub>CC</sub> Supply Undervoltage Positive Going Threshold	V <sub>CCUV+</sub>	7.6	8.4	9.8	V	_
V <sub>CC</sub> Supply Undervoltage Negative Going Threshold	V <sub>CCUV</sub> -	6.9	7.8	9.0	V	—
V and V Lindervaltage Livetoresia	V <sub>CCUVH</sub>	—	0.6	—	V	-
$V_{CC}$ and $V_{BS}$ Undervoltage Hysteresis	V <sub>BSUVH</sub>	—	0.6	_	V	—
Output High Short Circuit Pulsed Current	I <sub>O+</sub>	3.5	4.5	_	А	$V_0 = 0V, PW \le 10ms$
Output Low Short Circuit Pulsed Current	I <sub>O-</sub>	3.5	4.5	_	А	$V_0$ = 15V, PW $\leq$ 10ms

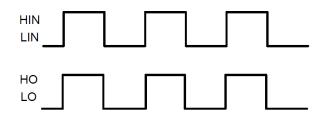
Note: 7. The V<sub>IN</sub> and I<sub>IN</sub> parameters are applicable to the two logic pins; HIN and LIN. The V<sub>O</sub> and I<sub>O</sub> parameters are applicable to the respective output pins: HO and LO.

### AC Electrical Characteristics (V<sub>BIAS</sub> (V<sub>CC</sub>, V<sub>BS</sub>) = 15V, C<sub>L</sub> = 1000pF, @T<sub>A</sub> = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-On Propagation Delay	ton	—	140	200	ns	$V_{\rm S} = 0V$
Turn-Off Propagation Delay	t <sub>OFF</sub>	—	140	200	ns	$V_{\rm S} = 0V$
Delay Matching, HO & LO Turn On/Off	t <sub>DM</sub>	—	0	50	ns	—
Turn-On Rise Time	t <sub>R</sub>	—	25	50	ns	$V_{\rm S} = 0V$
Turn-Off Fall Time	t <sub>F</sub>	—	20	45	ns	$V_{\rm S} = 0V$



# **Timing Waveforms**





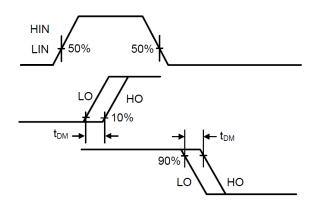


Figure 3. Delay Matching Waveform Definitions

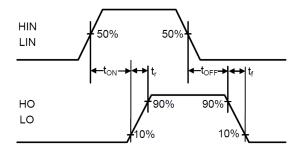


Figure 2. Switching Time Waveform Definitions



### Typical Performance Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

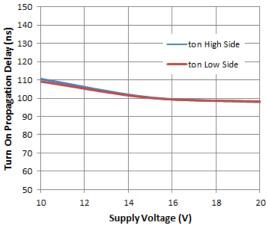


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

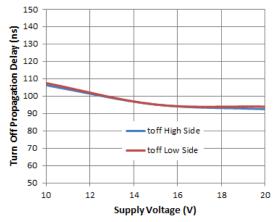


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

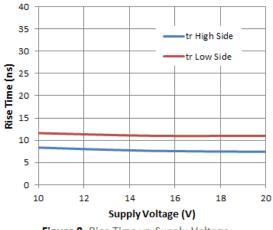


Figure 8. Rise Time vs. Supply Voltage

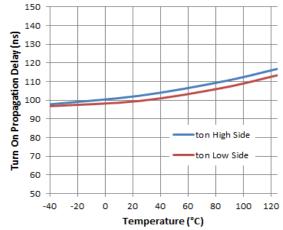


Figure 5. Turn-on Propagation Delay vs. Temperature

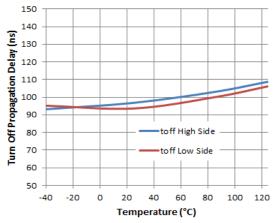


Figure 7. Turn-off Propagation Delay vs. Temperature

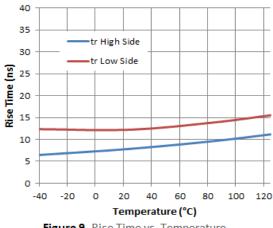


Figure 9. Rise Time vs. Temperature



### Typical Performance Characteristics (Cont.) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

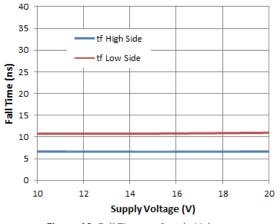


Figure 10. Fall Time vs. Supply Voltage

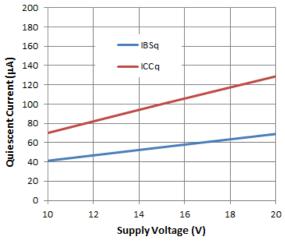


Figure 12. Quiescent Current vs. Supply Voltage

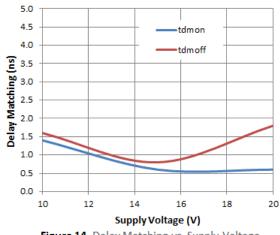
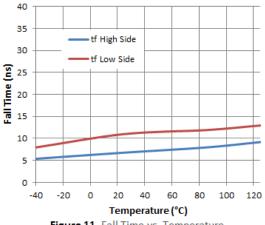
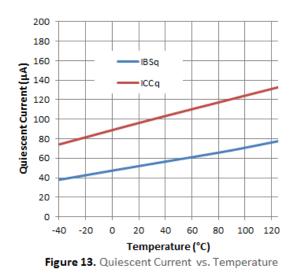


Figure 14. Delay Matching vs. Supply Voltage







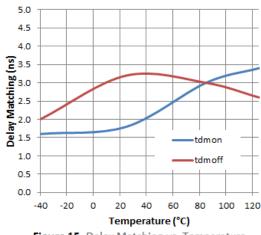


Figure 15. Delay Matching vs. Temperature



### Typical Performance Characteristics (Cont.) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

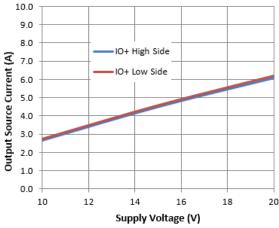


Figure 16. Output Source Current vs. Supply Voltage

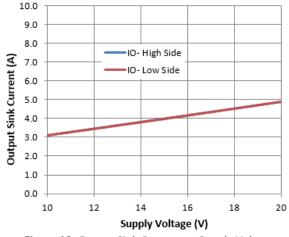


Figure 18. Output Sink Current vs. Supply Voltage

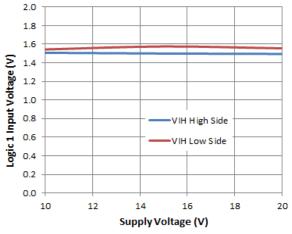


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

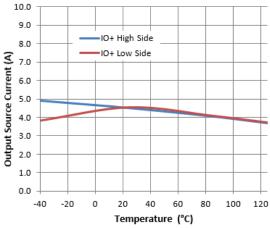
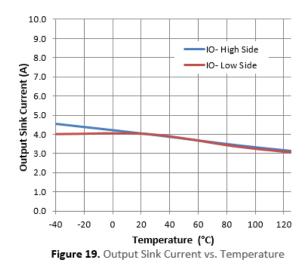


Figure 17. Output Source Current vs. Temperature



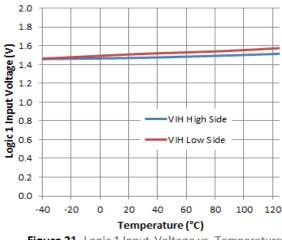
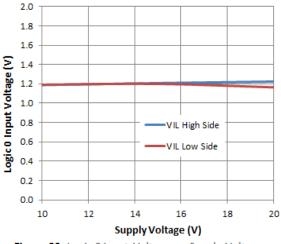


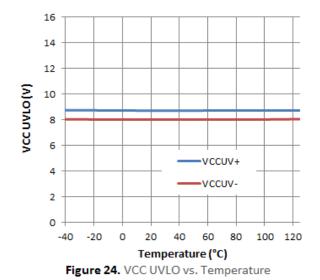
Figure 21. Logic 1 Input Voltage vs. Temperature



### Typical Performance Characteristics (Cont.) (@T<sub>A</sub> = +25°C, unless otherwise specified.)







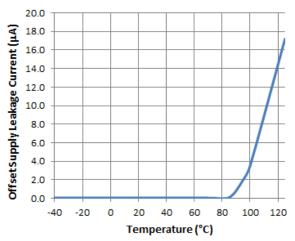


Figure 26. Offset Supply Leakage Current vs. Temperature

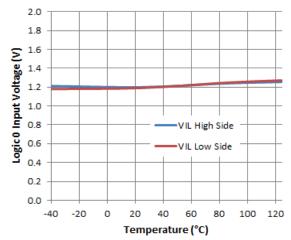
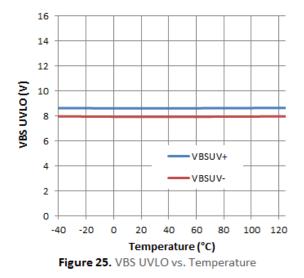


Figure 23. Logic 0 Input Voltage vs. Temperature

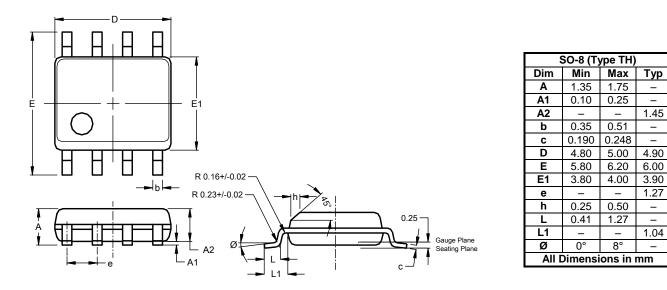




### **Package Outline Dimensions**

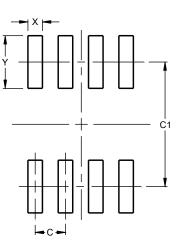
Please see http://www.diodes.com/package-outlines.html for the latest version.





### Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



000	(T	ти
SO-8	(Type	1 11)

Dimensions	Value (in mm)
C	1.27
C1	5.20
Х	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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